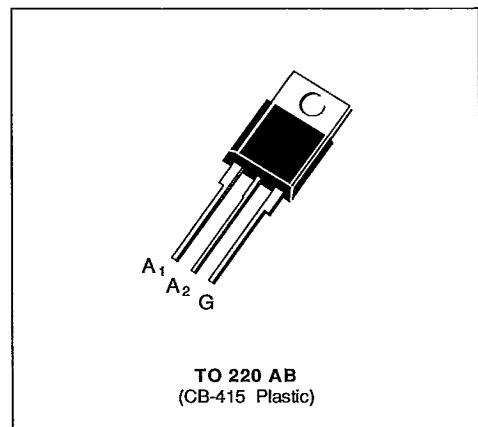


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SNUBBERLESS TRIACS

- $I_{TRMS} = 6 \text{ A}$ at $T_c = 100^\circ\text{C}$.
- $V_{DRM} : 200 \text{ V}$ to 800 V .
- $I_{GT} = 75 \text{ mA}$ (QI-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT : $I_{TSM} = 60 \text{ A}$.
- HIGH COMMUTATION CAPABILITY : $(di/dt)_c > 8 \text{ A / ms}$ without snubber.

**DESCRIPTION**

New range suited for applications such as phase control and static switching on inductive or resistive load.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value		Unit
I_{TRMS}	RMS on-state current (360 ° conduction angle)	$T_c = 100^\circ\text{C}$	6	A
I_{TSM}	Non repetitive surge peak on-state current (T_j initial = 25°C)	$t = 8.3 \text{ ms}$	63	A
		$t = 10 \text{ ms}$	60	
$I^2 t$	$I^2 t$ value	$t = 10 \text{ ms}$	18	$\text{A}^2 \text{ s}$
di/dt	Critical rate of rise of on-state current (1)	Repetitive $F = 50 \text{ Hz}$	20	$\text{A}/\mu\text{s}$
		Non Repetitive	100	
T_{stg} T_j	Storage and operating junction temperature range	$-40, +150$ $-40, +125$		$^\circ\text{C}$ $^\circ\text{C}$

Symbol	Parameter	BTB 06-					Unit
		200 AW	400 AW	600 AW	700 AW	800 AW	
V_{DRM}	Repetitive peak off-state voltage (2)	± 200	± 400	± 600	± 700	± 800	V

(1) Gate supply : $I_G = 750 \text{ mA}$ - $dI_G/dt = 1 \text{ A}/\mu\text{s}$.(2) $T_j = 125^\circ\text{C}$.

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (J - a)	Junction to ambient	60	°C/W
R _{th} (J - c) DC	Junction to case for DC	3.5	°C/W
R _{th} (J - c) AC	Junction to case for 360 ° conduction angle (F = 50 Hz)	2.7	°C/W

GATE CHARACTERISTICS (maximum values)

P_{GM} = 40 W (t = 10 µs) P_{G (AV)} = 1 W I_{GM} = 4 A (t = 10 µs) V_{GM} = 16 V (t = 10 µs).

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit	
I _{GT}	T _J = 25 °C	V _D = 12 V	R _L = 33 Ω	I-II-III	2		75	mA	
	Pulse duration > 20 µs								
V _{GT}	T _J = 25 °C	V _D = 12 V	R _L = 33 Ω	I-II-III			1.5	V	
	Pulse duration > 20 µs								
V _{GD}	T _J = 125 °C	V _D = V _{DRM}	R _L = 3.3 kΩ	I-II-III	0.2			V	
	Pulse duration > 20 µs								
I _{H*}	T _J = 25 °C	I _T = 100 mA					75	mA	
	Gate open	R _L = 140 Ω							
I _L	T _J = 25 °C	V _D = 12 V	I _G = 500 mA	I-III	75				
	Pulse duration > 20 µs			II	150				
V _{TM*}	T _J = 25 °C	I _{TM} = 8.5 A	t _p = 10 ms				1.75	V	
I _{DRM*}	T _J = 25 °C	V _{DRM} rated	Gate open				0.01	mA	
	T _J = 125 °C						2		
dV/dt*	T _J = 125 °C	Gate open Linear slope up to 0.67 V _{DRM}			750	1000		V/µs	
(di/dt) _c *	T _J = 125 °C	V _{DRM} rated Without snubber			8	16		A/ms	
t _{gt}	T _J = 25 °C	di _G /dt = 3.5 A/µs	I _G = 500 mA	I-II-III		2		µs	
	I _T = 8.5 A	V _D = V _{DRM}							

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

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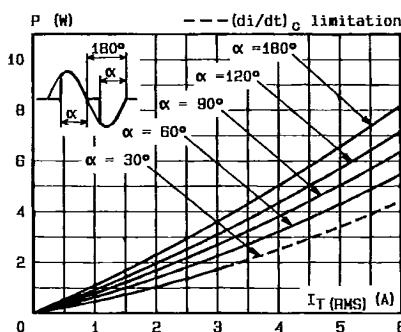


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($f = 60$ Hz).

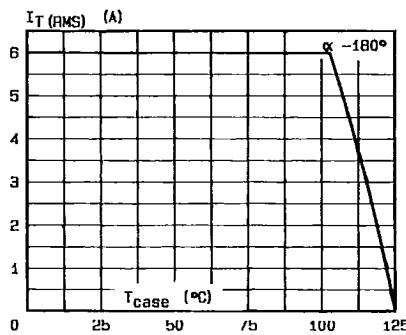


Fig.3 - RMS on-state current versus case temperature.

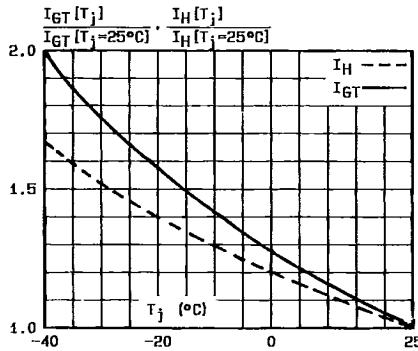


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

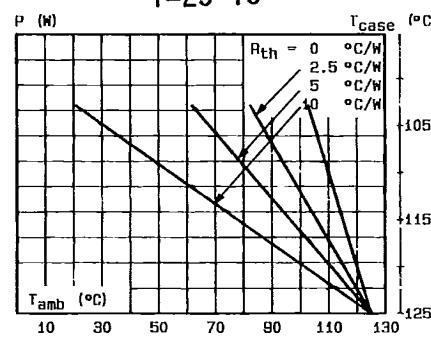


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

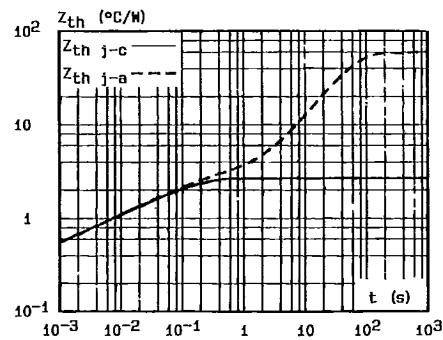


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

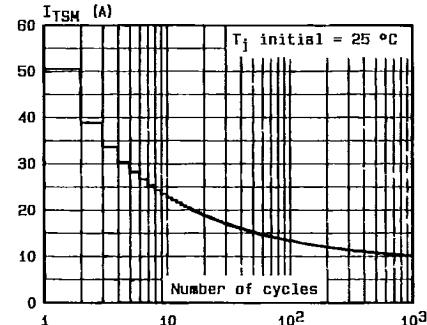


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

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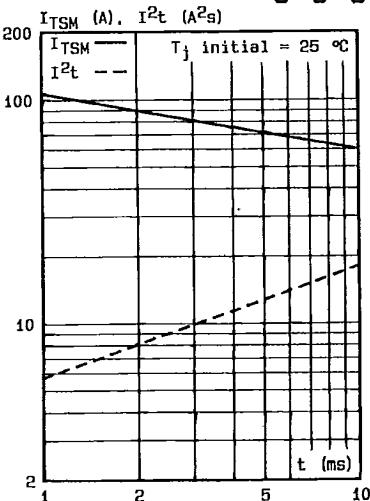


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

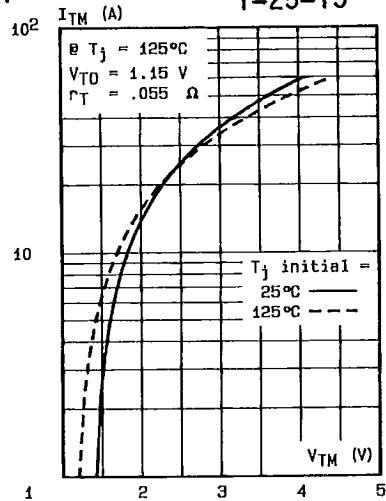
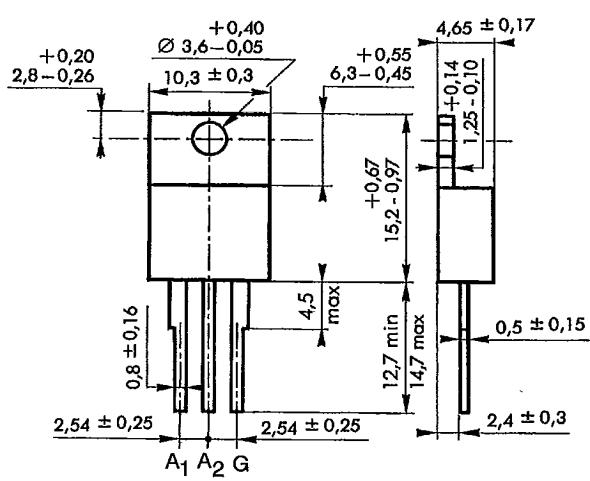


Fig.8 - On-state characteristics (maximum values).

PACKAGE MECHANICAL DATA

TO 220 AB (CB-415) Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g